NXP

Customer Information Notification	201805012I

Issue Date: 02-Jun-2018
Effective Date: 02-Jul-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

QUALITY

Management Summary
Final CAN FD Update for Product TJA1145

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[X] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

Final CAN FD Update for Product TJA1145

Description

Following the release of the ISO 11898-2:2016 and SAE J2284-1 to J2284-4 specifications, the datasheet of product TJA1145 is updated to support the final CAN FD requirements up to 2 Mbit/s. Also a new CAN FD C&S interoperability conformance report is available for this product, and a PPAP containing these documents is available on request.

No physical, design or test program change has been made to the TJA1145 product. Therefore its reliability and functionality is not affected. The improved performance through extended specifications can be guaranteed with the product (design) and test program as is.

The revision history of the datasheet details the changes made. The updated datasheet can be obtained from the NXP ePCN system you are subscribed to (see instruction below under the heading 'Remarks'). The updated datasheet will be published on the NXP website 30 days after publication of this CIN.

This change is explained in more detail in the attachment to this CIN (see instruction below under the heading 'Remarks').

Reason

NXP is committed to deliver products in compliance with ISO 11898-2:2016 and SAE J2284-1 to J2284-4 specifications and latest market requirements. This requires a datasheet update.

Identification of Affected Products

Product identification as shown in the first line of the top-side marking does not change.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No physical, design or test program change has been made to the TJA1145 product. Therefore its reliability and functionality is not affected.

Data Sheet Revision

A new datasheet will be issued

Related Notifications

Notification	Issue Date	Effective Date	Title
201403011I	27-Apr-2014	26-Jul-2014	UJA116x/TJA1145 support for CAN FD up to 2 Mbit/s and minor layout change
201605003I	15-Jun-2016	16-Jul-2016	HS-CAN datasheet update including ISO11898-2:2016 requirements
201710003I	22-Nov-2017	22-Dec-2017	Final CAN FD Update for Product TJA1043
201711021I	08-Dec-2017	08-Jan-2018	Final CAN FD Update for Products TJA1042 and TJA1051
201706001IU01	08-Dec-2017	08-Jan-2018	Final CAN FD Update for Mantis Products TJA1044, TJA1057 and TJA1046, and Introduction TJA1044 VIO
201712011I	03-Feb-2018	03-Mar-2018	Final CAN FD Update for Products TJA1049, TJA1059 and TJA1052i
201803023I	28-Mar-2018	28-Apr-2018	Final CAN FD Update for Product TJA1048

Remarks

Please use the link 'view online' above under the heading 'Additional information' to log in to the NXP ePCN system you're subscribed to, in order to obtain the updated datasheet, and attachment from the tab 'Files'. The datasheet will also be published in one month on the NXP website (www.nxp.com).

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

In the NXP ePCN system on the tab 'Products' you can see a list of your affected part numbers.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Affected Part Numbers

TJA1145T/FDJ

TJA1145TK/FDJ

TJA1145TKJ